

FEATURES

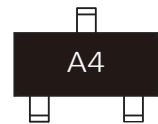
- | Fast Switching Speed

- | For General Purpose Switching Applications

- | High Conductance



SOT-23



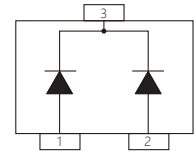
Marking

MECHANICAL DATA

- | SOT-23 Small Outline Plastic Package

- | Polarity: Color band denotes cathode end

- | Mounting Position: Any



Schematic Symbol

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

MAXIMUM RATINGS (T_A = 25°C)

Parameter	Symbol	Value	Unit
Reverse Breakdown Voltage	V _{RM}	70	V
DC Blocking Voltage	V _R	70	V
Forward Current	I _F	200	mA
Repetitive Peak Forward Current	I _{FRM}	500	mA
Thermal Resistance from Junction to Ambient	R _{θJA}	556	°C/W
Non-Repetitive Peak Forward Surge Current @t=8.3ms	I _{FSM}	2.0	A
Power Dissipation	P _D	225	mW
Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

ELECTRICAL CHARACTERISTICS($T_A=25^\circ\text{C}$)

Parameter	Test Condition	Symbol	Min.	Max.	Unit
Reverse breakdown Voltage	$I_R = 100\mu\text{A}$	V_R	70		V
Reverse Current	$V_R = 70\text{V}$	I_R		2.5	μA
Forward Voltage	$I_F = 1\text{mA}$	V_{F1}		0.715	V
	$I_F = 10\text{mA}$	V_{F2}		0.855	V
	$I_F = 50\text{mA}$	V_{F3}		1	V
	$I_F = 150\text{mA}$	V_{F4}		1.25	V
Capacitance between terminals	$V_R = 0\text{V}, f = 1\text{MHz}$	C_T		1.5	pF
Reverse Recovery Time	$I_F = I_R = 10\text{mA}$ $I_{rr} = 0.1 \times I_{R_L} R_L = 100\Omega$	t_{rr}		6	nS

CHARACTERISTIC CURVES

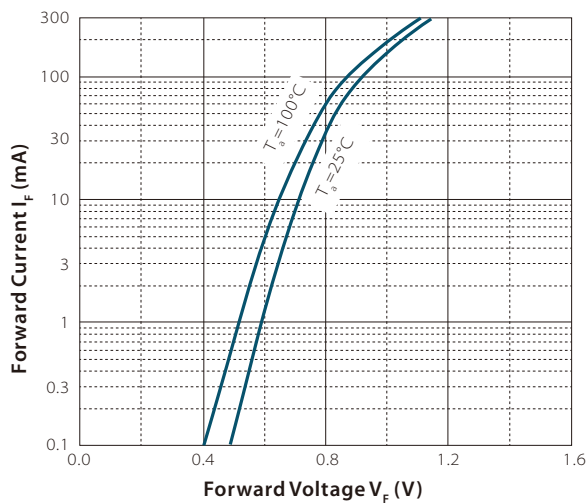
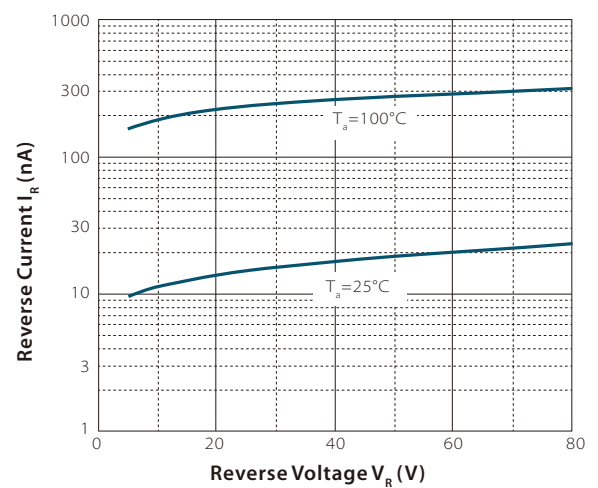
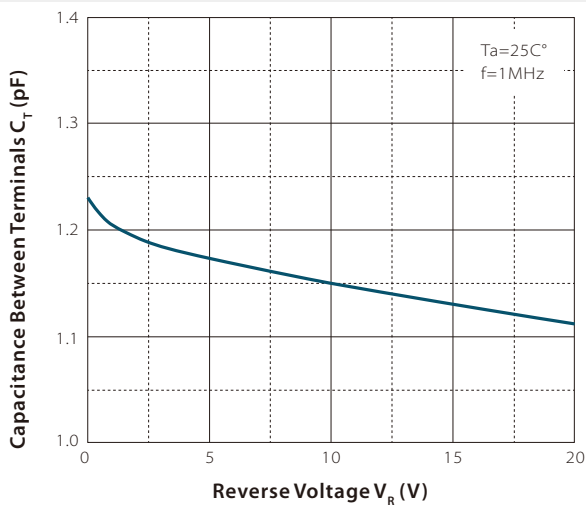
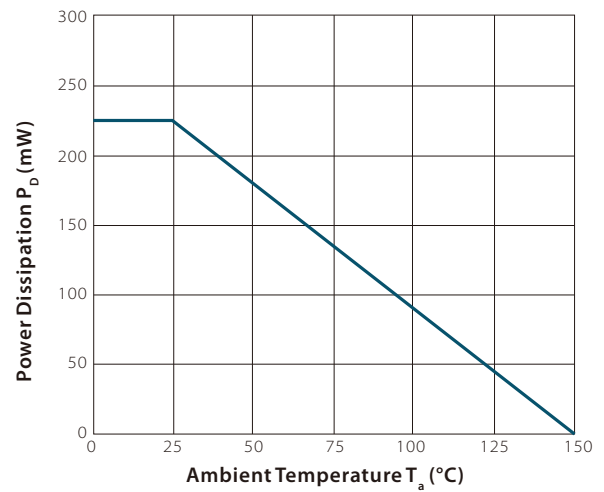
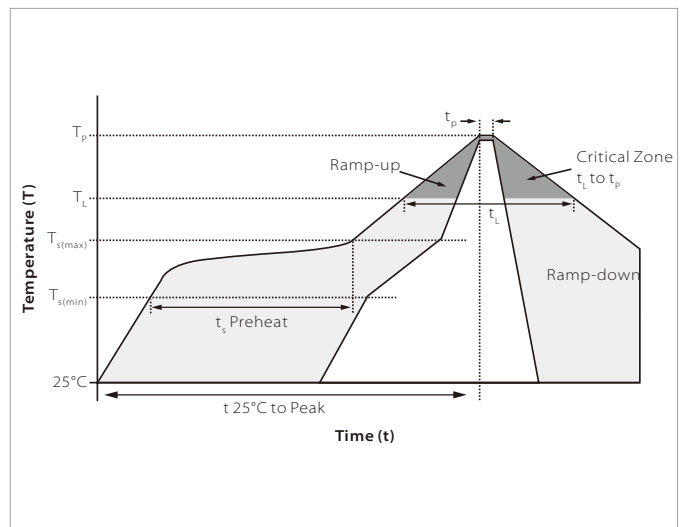
Fig 1. Forward Characteristics

Fig 2. Reverse Characteristics


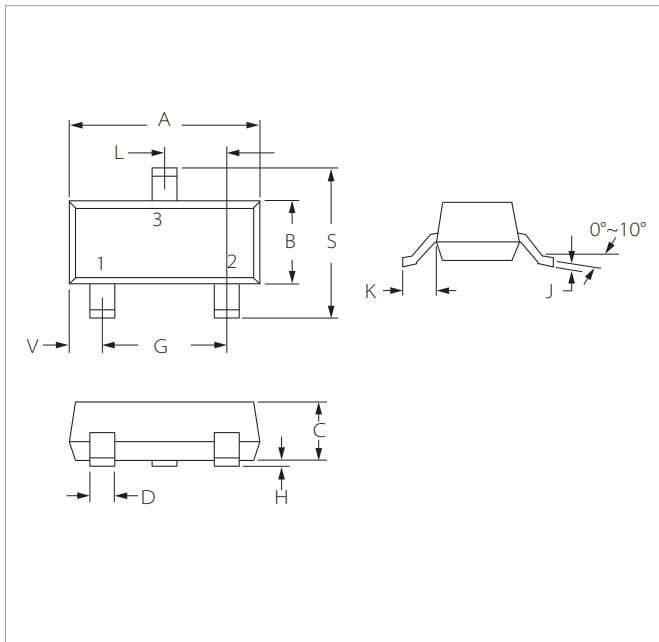
Fig 3. Capacitance Characteristics

Fig 4. Power Derating Curve


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(\text{min})}$)	150 $^\circ\text{C}$
	Temperature Max ($T_{s(\text{max})}$)	200 $^\circ\text{C}$
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3 $^\circ\text{C}/\text{second}$ max
$T_{s(\text{max})}$ to T_L - Ramp-up Rate		3 $^\circ\text{C}/\text{second}$ max
Reflow	Temperature (T_L) (Liquidus)	217 $^\circ\text{C}$
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 $^\circ\text{C}$
Time within 5 $^\circ\text{C}$ of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6 $^\circ\text{C}/\text{second}$ max
Time 25 $^\circ\text{C}$ to peak Temperature (T_p)		8 minutes max.
Do not exceed		260 $^\circ\text{C}$

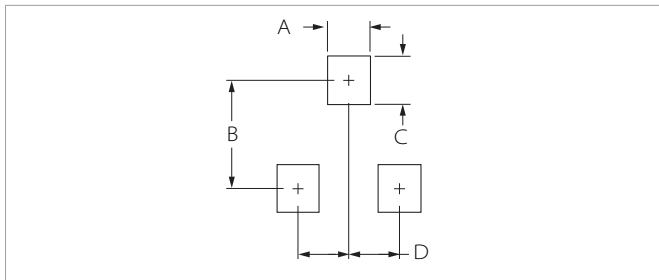


SOT-23 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.80	3.04	0.110	0.120
B	1.20	1.40	0.047	0.055
C	0.89	1.11	0.035	0.044
D	0.37	0.50	0.015	0.020
G	1.78	2.04	0.070	0.081
H	0.01	0.100	0.001	0.004
J	0.085	0.180	0.003	0.007
K	0.35	0.69	0.014	0.029
L	0.89	1.02	0.035	0.040
S	2.10	2.64	0.083	0.104
V	0.45	0.60	0.018	0.024

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.71	0.97	0.028	0.038
B	1.88	2.13	0.074	0.084
C	0.71	0.97	0.028	0.038
D	0.81	1.07	0.032	0.042

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
BAV70	SOT-23	3000PCS	7"

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